18. The TSV barrier layer polishing slurry of claim 1, wherein said oxidizing agents are peroxide or persulfide.

19. The TSV barrier layer polishing slurry of claim 18, where said oxidizing agents are one or more of the hydrogen peroxide, the sodium peroxide, the potassium peroxide, the benzoyl peroxide, the sodium persulfate, the potassium persulfate and the ammonium persulfate. ~~(please make sure each oxidizing agent should be mentioned in the examples)~~

20. The TSV barrier layer polishing slurry of claim 1, wherein said polishing slurry also includes anti-mold and anti-bacteria agents.

21. The TSV barrier layer polishing slurry of claim 20, wherein said anti-mold and anti-bacteria agent is quaternary ammonium salt.

22. The TSV barrier layer polishing slurry of claim 1, wherein the pH of said polishing slurry is 2-5.

23. The TSV barrier layer polishing slurry of claim 22, wherein the pH of said polishing slurry is 3-4.

24. The TSV barrier layer polishing slurry of claim 1, wherein concentration of said silicon nitride inhibitors is from 50ppm to 0.1%.